

# Triple Buffer with Open Drain Outputs

## NL37WZ07

The NL37WZ07 is a high performance triple buffer with open drain outputs operating from a 1.65 V to 5.5 V supply.

### Features

- Designed for 1.65 V to 5.5 V V<sub>CC</sub> Operation
- 2.1 ns t<sub>PD</sub> at V<sub>CC</sub> = 5 V (Typ)
- Inputs/Outputs Overvoltage Tolerant up to 5.5 V
- I<sub>OFF</sub> Supports Partial Power Down Protection
- Source/Sink 24 mA at 3.0 V
- Available in US8, UDFN8 and UQFN8 Packages
- Chip Complexity < 100 FETs
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

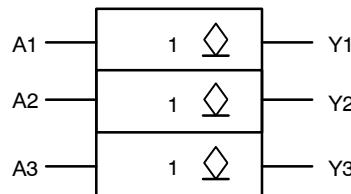
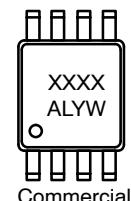


Figure 1. Logic Symbol

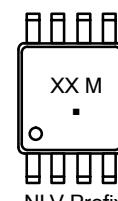


**US8**  
US SUFFIX  
CASE 493

### MARKING DIAGRAMS



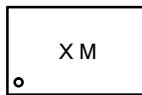
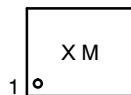
Commercial



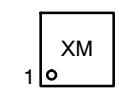
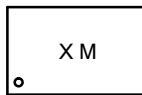
NLV Prefix



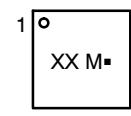
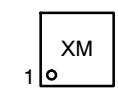
**UDFN8, 1.45x1.0**  
MU3 SUFFIX  
CASE 517BZ



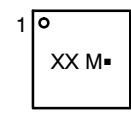
**UDFN8, 1.95x1.0**  
MU1 SUFFIX  
CASE 517CA



**UQFN8, 1.4x1.2**  
MQ2 SUFFIX  
CASE 523AS



**UQFN8, 1.6x1.6**  
MQ1 SUFFIX  
CASE 523AN



X, XX, XXXX	= Specific Device Code
A	= Assembly Location
L	= Lot Code
Y	= Year Code
W	= Week Code
M	= Date Code
▪	= Pb-Free Package

### ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 6 of this data sheet.

# NL37WZ07

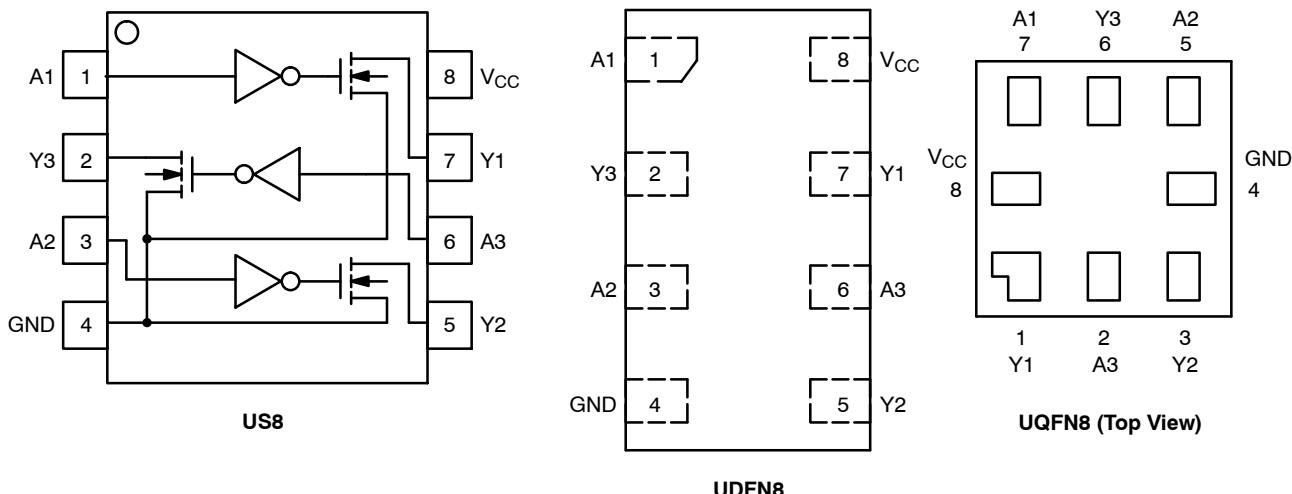


Figure 2. Pinout

## PIN ASSIGNMENT

Pin	US8 / UDFN8	UQFN8
1	A1	Y1
2	Y3	A3
3	A2	Y2
4	GND	GND
5	Y2	A2
6	A3	Y3
7	Y1	A1
8	V <sub>CC</sub>	V <sub>CC</sub>

## FUNCTION TABLE

A Input	Y Output
L	L
H	Z

## MAXIMUM RATINGS

Symbol	Characteristics	Value	Unit
V <sub>CC</sub>	DC Supply Voltage	NLV −0.5 to +7.0 −0.5 to +6.5	V
V <sub>IN</sub>	DC Input Voltage	NLV −0.5 to +7.0 −0.5 to +6.5	V
V <sub>OUT</sub>	DC Output Voltage (NLV) Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V <sub>CC</sub> = 0 V)	−0.5 to V <sub>CC</sub> + 0.5 −0.5 to +7.0 −0.5 to +7.0	V
	DC Output Voltage Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V <sub>CC</sub> = 0 V)	−0.5 to V <sub>CC</sub> + 0.5 −0.5 to +6.5 −0.5 to +6.5	V
I <sub>IK</sub>	DC Input Diode Current V <sub>IN</sub> < GND	−50	mA
I <sub>OK</sub>	DC Output Diode Current V <sub>OUT</sub> < GND	−50	mA
I <sub>OUT</sub>	DC Output Source/Sink Current	±50	mA
I <sub>CC</sub> or I <sub>GND</sub>	DC Supply Current per Supply Pin or Ground Pin	±100	mA
T <sub>STG</sub>	Storage Temperature Range	−65 to +150	°C
T <sub>L</sub>	Lead Temperature, 1 mm from Case for 10 secs	260	°C
T <sub>J</sub>	Junction Temperature Under Bias	+150	°C
θ <sub>JA</sub>	Thermal Resistance (Note 2)	US8 UQFN8 UDFN8 250 210 231	°C/W
P <sub>D</sub>	Power Dissipation in Still Air	US8 UQFN8 UDFN8 500 595 541	mW
MSL	Moisture Sensitivity	Level 1	—
F <sub>R</sub>	Flammability Rating	Oxygen Index: 28 to 34	UL 94 V–0 @ 0.125 in
V <sub>ESD</sub>	ESD Withstand Voltage (Note 3)	Human Body Model Charged Device Model 2000 1000	V
I <sub>Latchup</sub>	Latchup Performance (Note 4)	±100	mA

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- Applicable to devices with outputs that may be tri–stated.
- Measured with minimum pad spacing on an FR4 board, using 10mm–by–1inch, 2 ounce copper trace no air flow per JESD51–7.
- HBM tested to ANSI/ESDA/JEDEC JS–001–2017. CDM tested to EIA/JESD22–C101–F. JEDEC recommends that ESD qualification to EIA/JESD22–A115–A (Machine Model) be discontinued per JEDEC/JEP172A.
- Tested to EIA/JESD78 Class II.

## RECOMMENDED OPERATING CONDITIONS

Symbol	Characteristics	Min	Max	Unit
V <sub>CC</sub>	Positive DC Supply Voltage	1.65	5.5	V
V <sub>IN</sub>	DC Input Voltage	0	5.5	V
V <sub>OUT</sub>	DC Output Voltage Active–Mode (High or Low State) Tri–State Mode (Note 1) Power–Down Mode (V <sub>CC</sub> = 0 V)	0	V <sub>CC</sub>	
		0	5.5	
T <sub>A</sub>	Operating Temperature Range	−55	+125	°C
t <sub>r</sub> , t <sub>f</sub>	Input Rise and Fall Time V <sub>CC</sub> = 1.65 V to 1.95 V V <sub>CC</sub> = 2.3 V to 2.7 V V <sub>CC</sub> = 3.0 V to 3.6 V V <sub>CC</sub> = 4.5 V to 5.5 V	0	20 20 10 5	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

## DC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			-55°C ≤ T <sub>A</sub> ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
V <sub>IH</sub>	High-Level Input Voltage (NLV)		1.65 to 1.95	0.75 × V <sub>CC</sub>	—	—	0.75 × V <sub>CC</sub>	—	V
			2.3 to 5.5	0.70 × V <sub>CC</sub>	—	—	0.70 × V <sub>CC</sub>	—	
	High-Level Input Voltage		1.65 to 1.95	0.65 × V <sub>CC</sub>	—	—	0.65 × V <sub>CC</sub>	—	V
			2.3 to 5.5	0.70 × V <sub>CC</sub>	—	—	0.70 × V <sub>CC</sub>	—	
V <sub>IL</sub>	Low-Level Input Voltage (NLV)		1.65 to 1.95	—	—	0.25 × V <sub>CC</sub>	—	0.25 × V <sub>CC</sub>	V
			2.3 to 5.5	—	—	0.30 × V <sub>CC</sub>	—	0.30 × V <sub>CC</sub>	
	Low-Level Input Voltage		1.65 to 1.95	—	—	0.35 × V <sub>CC</sub>	—	0.35 × V <sub>CC</sub>	V
			2.3 to 5.5	—	—	0.30 × V <sub>CC</sub>	—	0.30 × V <sub>CC</sub>	
V <sub>OL</sub>	Low-Level Output Voltage	V <sub>IN</sub> = V <sub>IH</sub> or V <sub>IL</sub> I <sub>OL</sub> = 100 µA I <sub>OL</sub> = 4 mA I <sub>OL</sub> = 8 mA I <sub>OL</sub> = 12 mA I <sub>OL</sub> = 16 mA I <sub>OL</sub> = 24 mA I <sub>OL</sub> = 32 mA	1.65 to 5.5	— 1.65 2.3 2.7 3.0 3.0 4.5	— 0.08 0.2 0.22 0.28 0.38 0.42	0.1 0.24 0.3 0.4 0.4 0.55 0.55	— — — — — — —	0.1 0.24 0.3 0.4 0.4 0.55 0.55	V
I <sub>IN</sub>	Input Leakage Current	V <sub>IN</sub> = 5.5 V or GND	1.65 to 5.5	—	—	±0.1	—	±1.0	µA
I <sub>OZ</sub>	3-State Output Leakage Current	V <sub>OUT</sub> = 0 V to 5.5 V	1.65 to 5.5	—	—	±0.5	—	±5.0	µA
I <sub>OFF</sub>	Power Off Leakage Current	V <sub>IN</sub> = 5.5 V or V <sub>OUT</sub> = 5.5 V	0	—	—	1.0	—	10	µA
I <sub>CC</sub>	Quiescent Supply Current	V <sub>IN</sub> = V <sub>CC</sub> or GND	5.5	—	—	1.0	—	10	µA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

## AC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Condition	V <sub>CC</sub> (V)	T <sub>A</sub> = 25°C			-55°C ≤ T <sub>A</sub> ≤ 125°C		Units
				Min	Typ	Max	Min	Max	
t <sub>PZL</sub>	Propagation Delay, A to Y (Figures 3 and 4)		1.65 to 1.95	—	6.0	9.0	—	9.5	ns
			2.3 to 2.7	—	3.6	6.1	—	6.5	
			3.0 to 3.6	—	2.7	5.6	—	6.0	
			4.5 to 5.5	—	2.1	4.4	—	4.8	
t <sub>PLZ</sub>	Propagation Delay, A to Y (Figures 3 and 4)		1.65 to 1.95	—	4.0	9.0	—	9.5	ns
			2.3 to 2.7	—	2.8	6.1	—	6.5	
			3.0 to 3.6	—	2.5	5.6	—	6.0	
			4.5 to 5.5	—	2.2	4.4	—	4.8	

## CAPACITIVE CHARACTERISTICS

Symbol	Parameter	Condition	Typical	Units
C <sub>IN</sub>	Input Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	2.5	pF
C <sub>OUT</sub>	Output Capacitance	V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	2.5	pF
C <sub>PD</sub>	Power Dissipation Capacitance (Note 5)	10 MHz, V <sub>CC</sub> = 3.3 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub> 10 MHz, V <sub>CC</sub> = 5.5 V, V <sub>IN</sub> = 0 V or V <sub>CC</sub>	9 11	pF

5. C<sub>PD</sub> is defined as the value of the internal equivalent capacitance which is calculated from the operating current consumption without load. Average operating current can be obtained by the equation: I<sub>CC(OPR)</sub> = C<sub>PD</sub> • V<sub>CC</sub> • f<sub>in</sub> + I<sub>CC</sub>. C<sub>PD</sub> is used to determine the no-load dynamic power consumption; P<sub>D</sub> = C<sub>PD</sub> • V<sub>CC</sub><sup>2</sup> • f<sub>in</sub> + I<sub>CC</sub> • V<sub>CC</sub>.

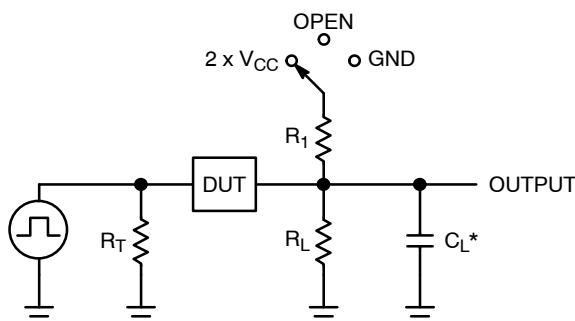


Figure 3. Test Circuit

Test	Switch Position	$C_L$ , pF	$R_L$ , $\Omega$	$R_1$ , $\Omega$
$t_{PLH} / t_{PHL}$	Open	See AC Characteristics Table		
$t_{PLZ} / t_{PZL}$	$2 \times V_{CC}$	50	500	500
$t_{PHZ} / t_{PZH}$	GND	50	500	500

X = Don't Care

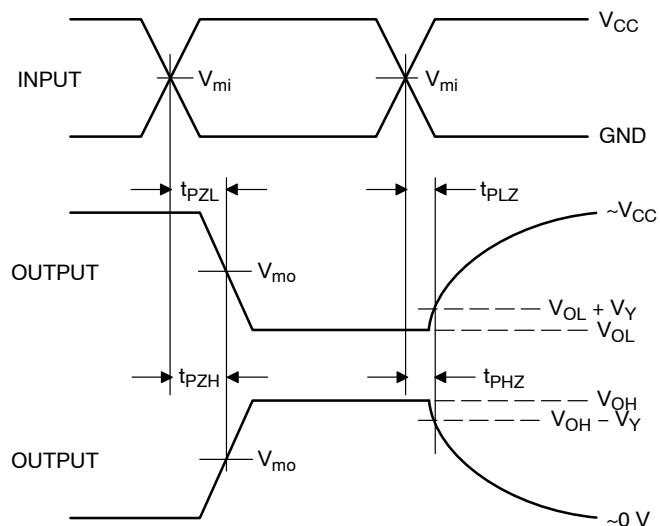
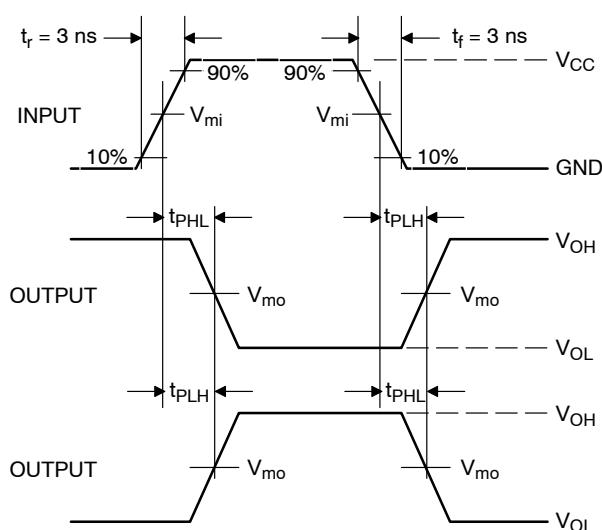


Figure 4. Switching Waveforms

$V_{CC}$ , V	$V_{mi}$ , V	$V_{mo}$ , V		$V_Y$ , V
		$t_{PLH}, t_{PHL}$	$t_{PZL}, t_{PLZ}, t_{PZH}, t_{PHZ}$	
1.65 to 1.95	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
2.3 to 2.7	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.15
3.0 to 3.6	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3
4.5 to 5.5	$V_{CC}/2$	$V_{CC}/2$	$V_{CC}/2$	0.3

# NL37WZ07

## DEVICE ORDERING INFORMATION

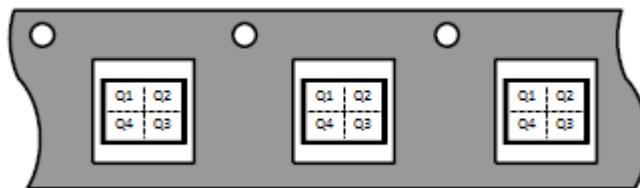
Device	Packages	Specific Device Code	Pin 1 Orientation (See below)	Shipping <sup>†</sup>
NL37WZ07USG	US8	L7	Q4	3000 / Tape & Reel
NLV37WZ07USG*	US8	L7	Q4	3000 / Tape & Reel
NL37WZ07MQ1TCG (In Development)	UQFN8, 1.6 x 1.6, 0.5P	TBD	TBD	3000 / Tape & Reel
NL37WZ07MU1TCG (In Development)	UDFN8, 1.95 x 1.0, 0.5P	TBD	TBD	3000 / Tape & Reel
NL37WZ07MU3TCG (In Development)	UDFN8, 1.45 x 1.0, 0.35P	TBD	TBD	3000 / Tape & Reel
NL37WZ07MQ2TCG (In Development)	UQFN8, 1.4 x 1.2, 0.4P	TBD	TBD	3000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

\*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable.

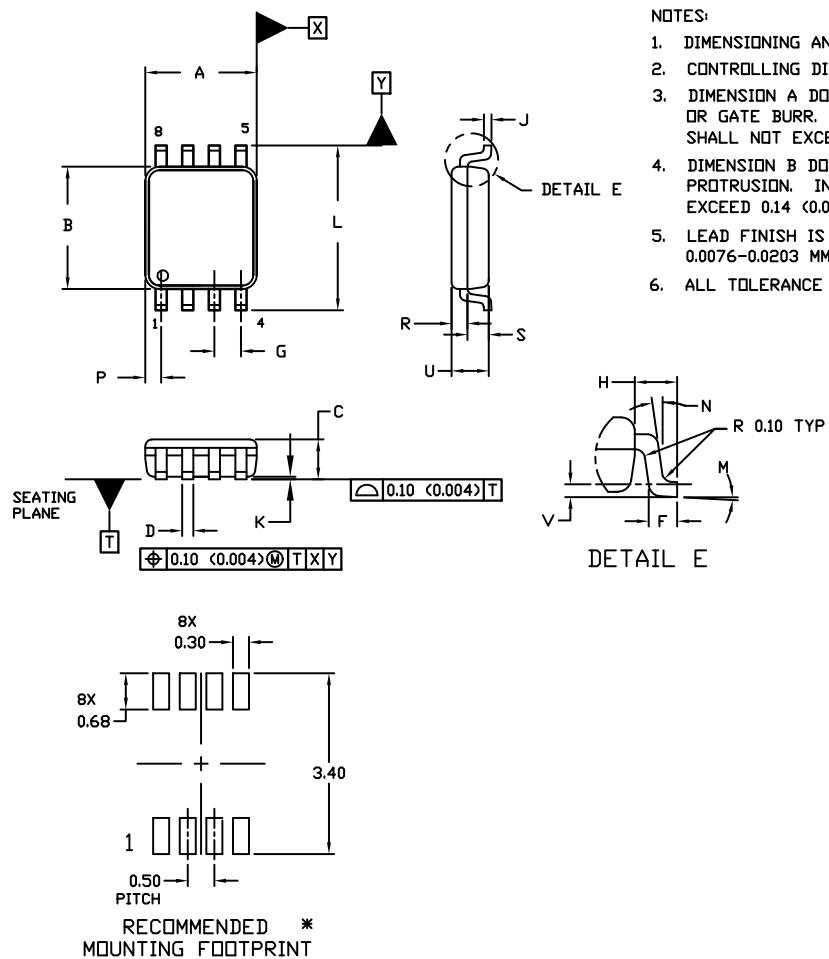
## Pin 1 Orientation in Tape and Reel

### Direction of Feed



## PACKAGE DIMENSIONS

**US8**  
CASE 493  
ISSUE F



## NOTES:

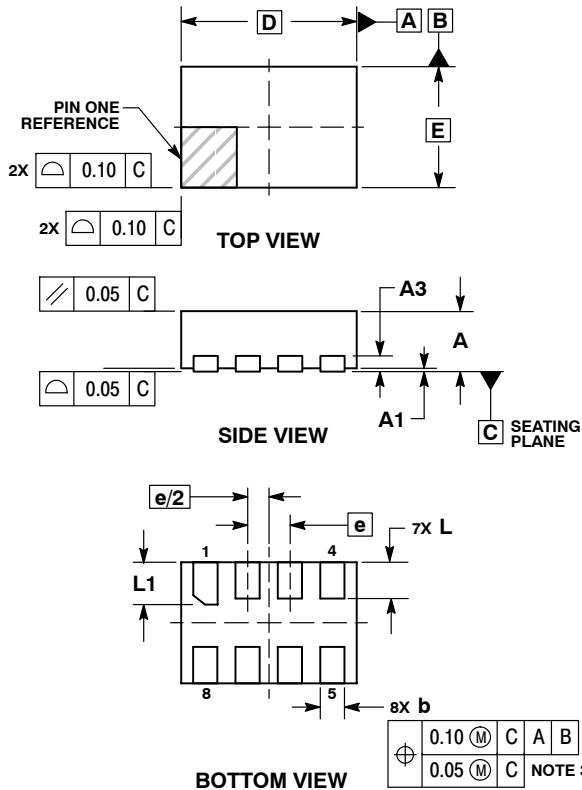
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSION, OR GATE BURR. MOLD FLASH, PROTRUSION, OR GATE BURR SHALL NOT EXCEED 0.14 (0.0055") PER SIDE.
4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH AND PROTRUSION SHALL NOT EXCEED 0.14 (0.0055") PER SIDE.
5. LEAD FINISH IS SOLDER PLATING WITH THICKNESS OF 0.0076-0.0203 MM (0.003-0.008").
6. ALL TOLERANCE UNLESS OTHERWISE SPECIFIED  $\pm 0.0508$  MM (0.002").

DIM	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	1.90	2.10	0.075	0.083
B	2.20	2.40	0.087	0.094
C	0.60	0.90	0.024	0.035
D	0.17	0.25	0.007	0.010
F	0.20	0.35	0.008	0.014
G	0.50	BSC	0.020	BSC
H	0.40	REF	0.016	REF
J	0.10	0.18	0.004	0.007
K	0.00	0.10	0.000	0.004
L	3.00	3.25	0.118	0.128
M	0°	6°	0°	6°
N	0°	10°	0°	10°
P	0.23	0.34	0.010	0.013
R	0.23	0.33	0.009	0.013
S	0.37	0.47	0.015	0.019
U	0.60	0.80	0.024	0.031
V	0.12	BSC	0.005	BSC

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## PACKAGE DIMENSIONS

**UDFN8, 1.45x1, 0.35P**  
CASE 517BZ-01  
ISSUE O

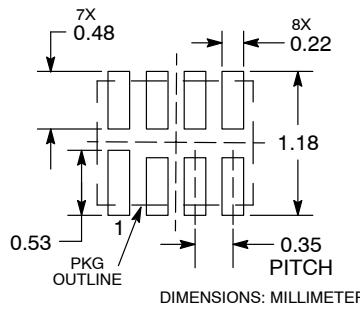


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.20 MM FROM TERMINAL TIP.
4. PACKAGE DIMENSIONS EXCLUSIVE OF BURRS AND MOLD FLASH.

MILLIMETERS		
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.45 BSC	
E	1.00 BSC	
e	0.35 BSC	
L	0.25	0.35
L1	0.30	0.40

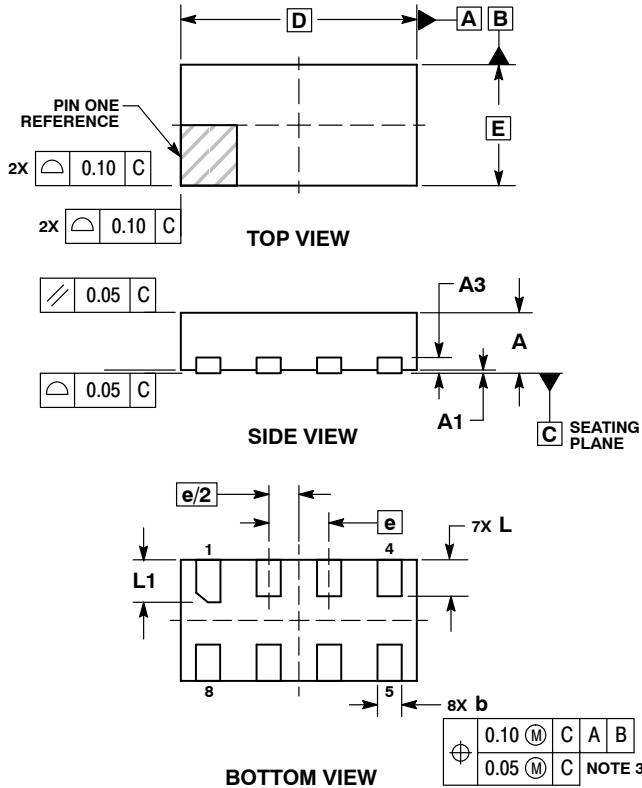
**RECOMMENDED  
SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

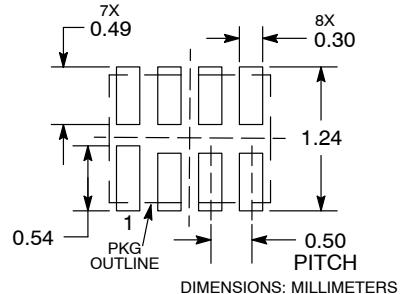
## PACKAGE DIMENSIONS

**UDFN8, 1.95x1, 0.5P**  
CASE 517CA-01  
ISSUE O



	MILLIMETERS	
DIM	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13	REF
b	0.15	0.25
D	1.95	BSC
E	1.00	BSC
e	0.50	BSC
L	0.25	0.35
L1	0.30	0.40

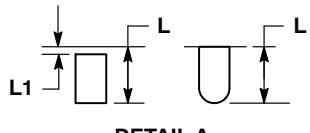
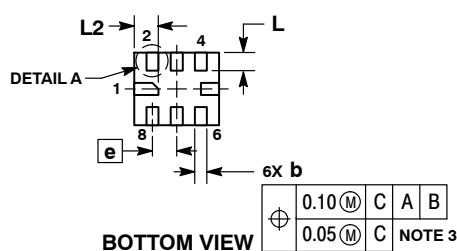
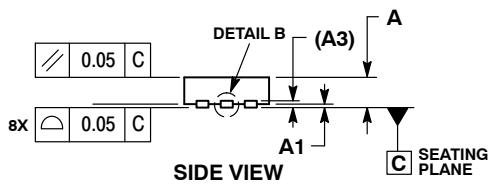
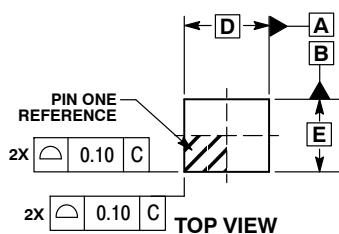
**RECOMMENDED  
SOLDERING FOOTPRINT\***



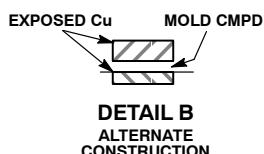
\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## PACKAGE DIMENSIONS

**UQFN8, 1.4x1.2, 0.4P**  
**CASE 523AS**  
**ISSUE A**

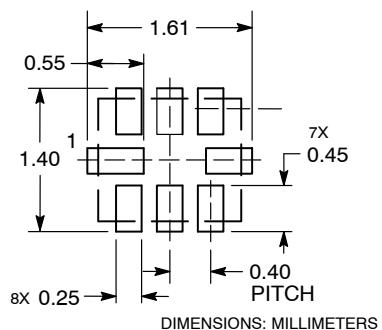


**DETAIL A**  
ALTERNATE  
CONSTRUCTIONS



NOTES:  
1. DIMENSIONING AND TOLERANCING PER  
ASME Y14.5M, 1994.  
2. CONTROLLING DIMENSION: MILLIMETERS.  
3. DIMENSION b APPLIES TO PLATED TERMINAL  
AND IS MEASURED BETWEEN 0.15 AND  
0.25 mm FROM THE TERMINAL TIP.

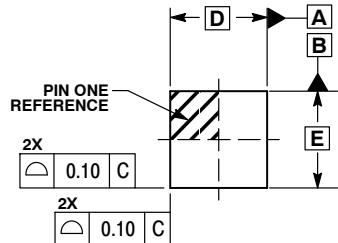
DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.55
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.40 BSC	
E	1.20 BSC	
L	0.20	0.40
L1	---	0.15
L2	0.30	0.50

**SOLDERING FOOTPRINT\***

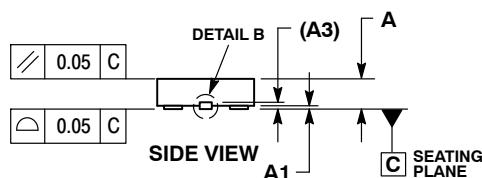
\*For additional information on our Pb-Free strategy  
and soldering details, please download the  
**onsemi** Soldering and Mounting  
Techniques Reference Manual, SOLDERRM/D.

## PACKAGE DIMENSIONS

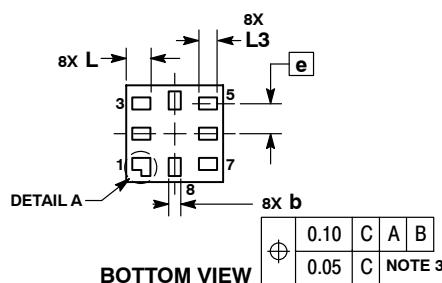
**UQFN8, 1.6x1.6, 0.5P**  
**CASE 523AN-01**  
**ISSUE O**



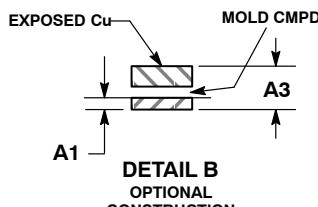
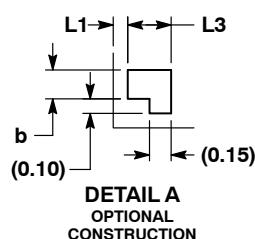
TOP VIEW



SIDE VIEW

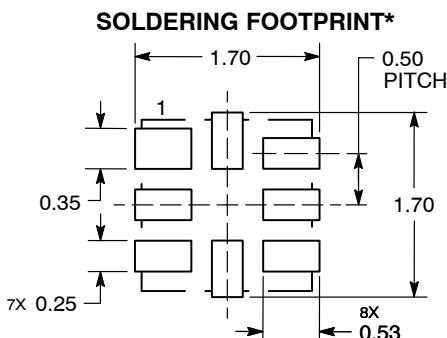


BOTTOM VIEW

DETAIL B  
OPTIONAL CONSTRUCTIONDETAIL A  
OPTIONAL CONSTRUCTION

NOTES:  
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.  
2. CONTROLLING DIMENSION: MILLIMETERS.  
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.

DIM	MILLIMETERS	
	MIN	MAX
A	0.45	0.60
A1	0.00	0.05
A3	0.13 REF	
b	0.15	0.25
D	1.60 BSC	
E	1.60 BSC	
e	0.50 BSC	
L	0.35	0.45
L1	—	0.15
L3	0.25	0.35



DIMENSIONS: MILLIMETERS

\*For additional information on our Pb-Free strategy and soldering details, please download the **onsemi** Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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